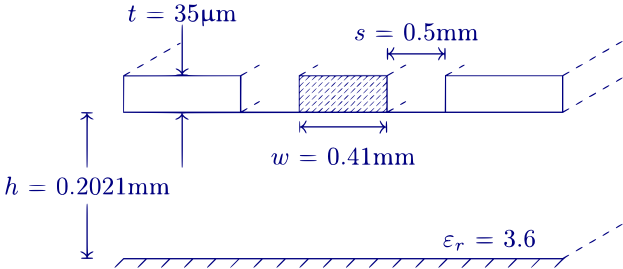


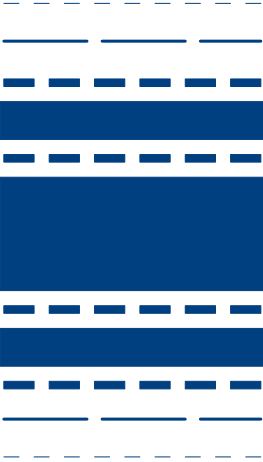
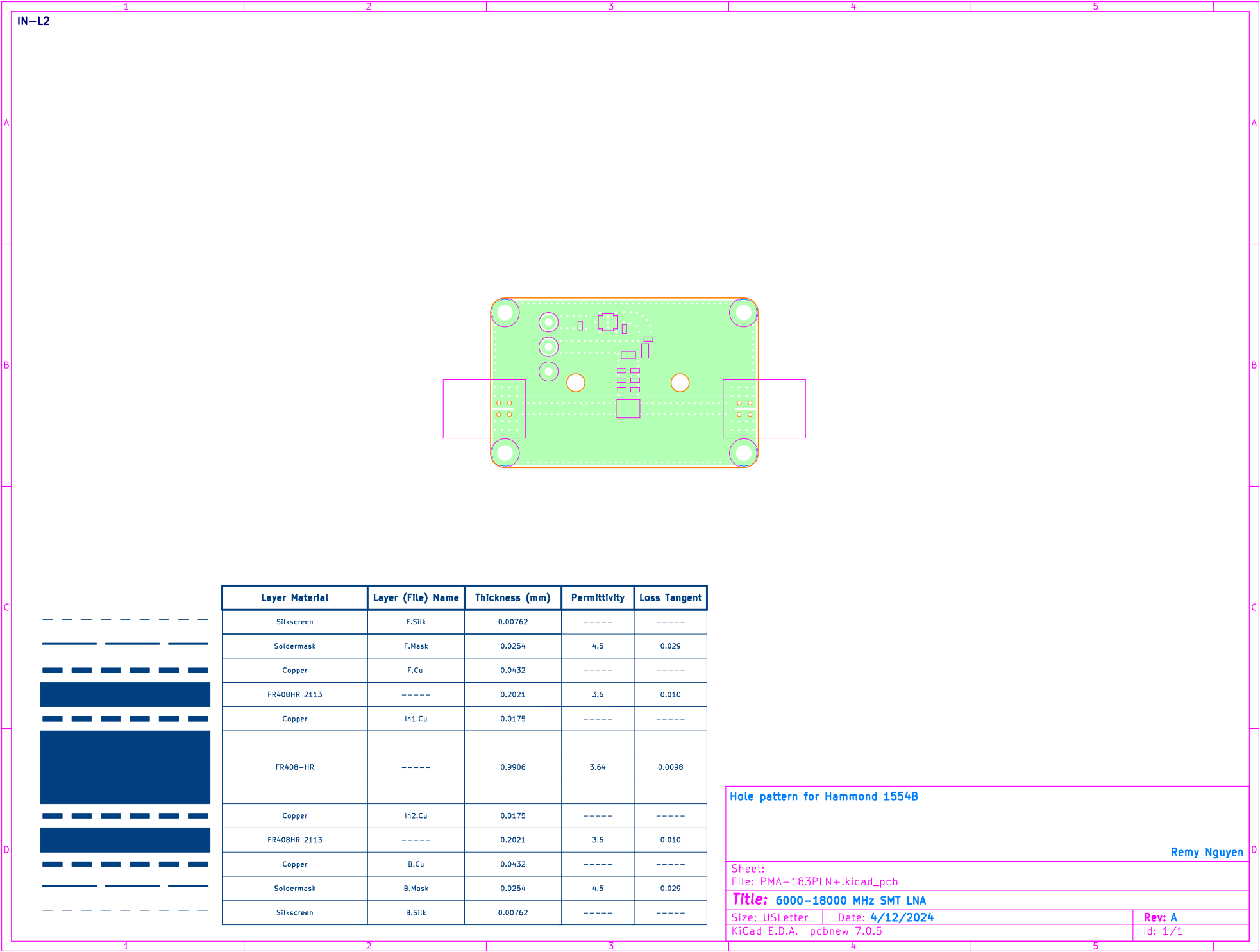
Layer Material	Layer (File) Name	Thickness (mm)	Permittivity	Loss Tangent
Silkscreen	F.Silk	0.00762	----	----
Soldermask	F.Mask	0.0254	4.5	0.029
Copper	F.Cu	0.0432	----	----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	In1.Cu	0.0175	----	----
FR408-HR	-----	0.9906	3.64	0.0098
Copper	In2.Cu	0.0175	----	----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	B.Cu	0.0432	----	----
Soldermask	B.Mask	0.0254	4.5	0.029
Silkscreen	B.Silk	0.00762	----	----



Hole pattern for Hammond 1554B

Remy Nguyen

Sheet:	
File: PMA-183PLN+.kicad_pcb	
Title: 6000-18000 MHz SMT LNA	
Size: USLetter	Date: 4/12/2024
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Id: 1/1	



Layer Material	Layer (File) Name	Thickness (mm)	Permittivity	Loss Tangent
Silkscreen	F.Silk	0.00762	-----	-----
Soldermask	F.Mask	0.0254	4.5	0.029
Copper	F.Cu	0.0432	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	In1.Cu	0.0175	-----	-----
FR408-HR	-----	0.9906	3.64	0.0098
Copper	In2.Cu	0.0175	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	B.Cu	0.0432	-----	-----
Soldermask	B.Mask	0.0254	4.5	0.029
Silkscreen	B.Silk	0.00762	-----	-----

Hole pattern for Hammond 1554B

Remy Nguyen

Sheet:
File: PMA-183PLN+.kicad_pcb

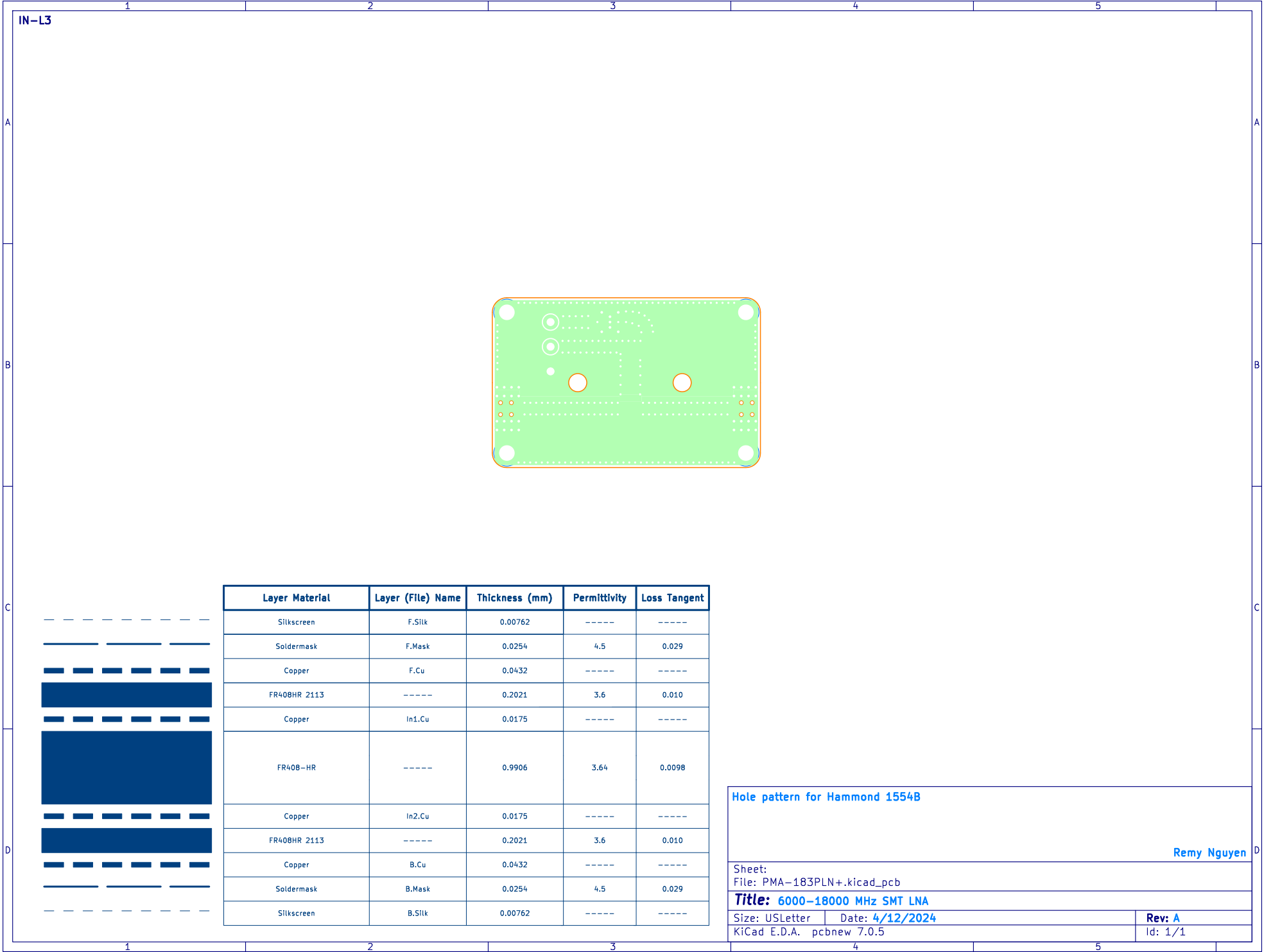
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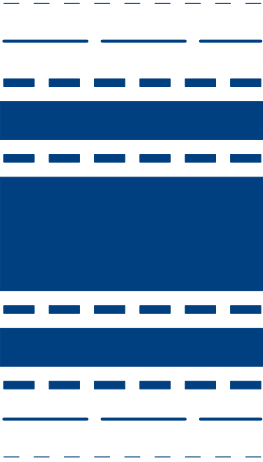
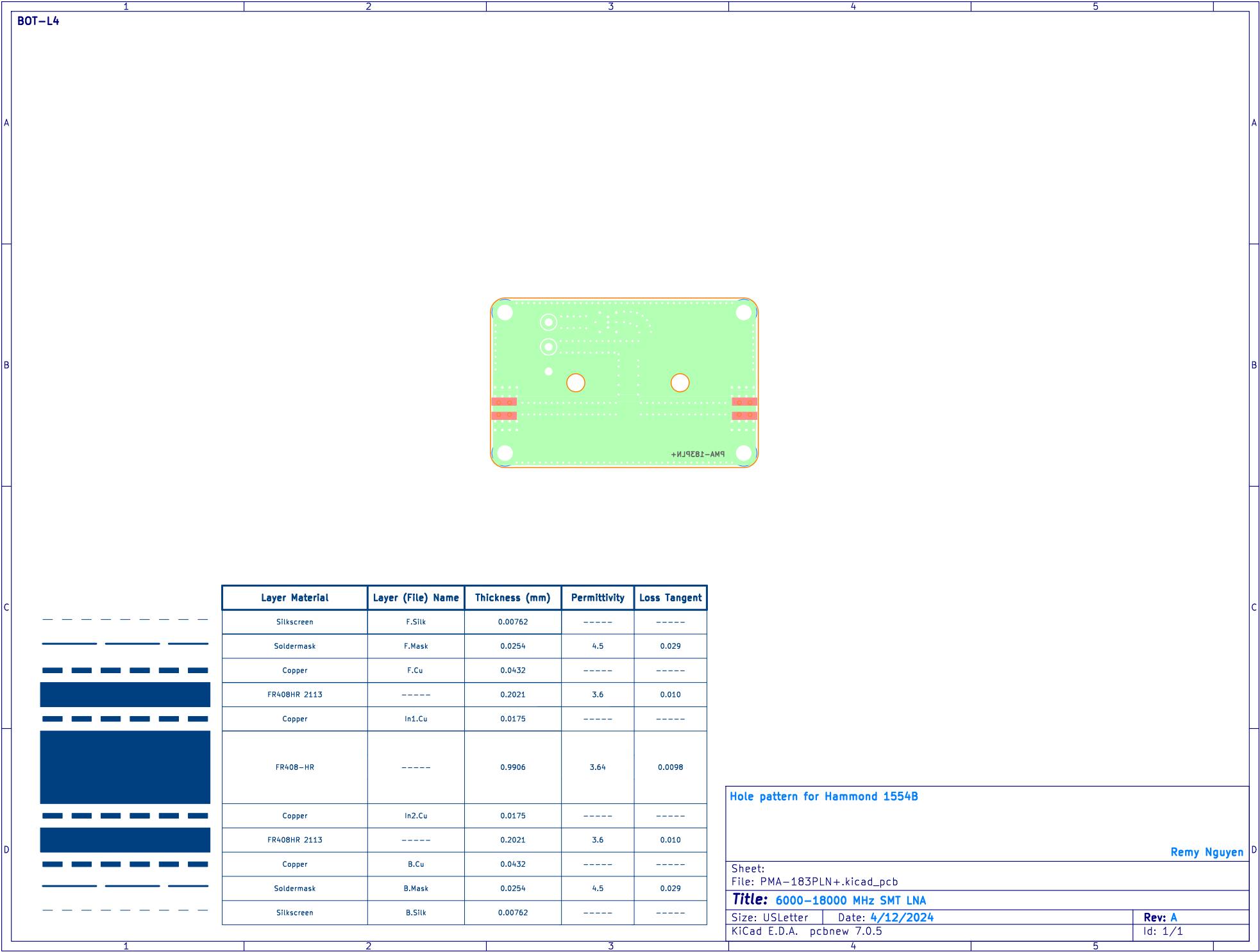
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KiCad E.D.A. pcbnew 7.0.5

Rev: A

Id: 1/1





Layer Material	Layer (File) Name	Thickness (mm)	Permittivity	Loss Tangent
Silkscreen	F.Silk	0.00762	-----	-----
Soldermask	F.Mask	0.0254	4.5	0.029
Copper	F.Cu	0.0432	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	In1.Cu	0.0175	-----	-----
FR408-HR	-----	0.9906	3.64	0.0098
Copper	In2.Cu	0.0175	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	B.Cu	0.0432	-----	-----
Soldermask	B.Mask	0.0254	4.5	0.029
Silkscreen	B.Silk	0.00762	-----	-----

Hole pattern for Hammond 1554B

Remy Nguyen

Sheet:
File: PMA-183PLN+.kicad_pcb

Title: 6000-18000 MHz SMT LNA

Size: USLetter Date: 4/12/2024 Rev: A

KiCad E.D.A. pcbnew 7.0.5 Id: 1/1